



MEMS/NEMS North America TC Chapter

SEMICON West 2017 Standards Meetings

Thursday, July 13

Marriott Marquis Hotel, San Francisco, California

15:30–17:30

AGENDA

	Time
1 Welcome/Call to Order	15:30
1.1 Introductions	
1.2 Required Elements (Membership Requirements, Antitrust and Intellectual Property Reminders, and Effective Meeting Guidelines)	
1.3 Agenda Review	
2 Review of Previous Meeting Minutes	15:40
3 Staff Report	15:45
4 Ballot Review	15:50
4.1 Document 5267 — New Standard, Specification for Microfluidic Port and Pitch Dimensions	
4.2 Document 6176 — Reapproval of SEMI MS1-0307 (Reapproved 0812), Guide to Specifying Wafer-Wafer Bonding Alignment Target	
4.3 Document 6177 — Reapproval of SEMI MS10-0912, Test Method to Measure Fluid Permeation Through MEMS Packaging Materials	
5 Subcommittee & Task Force Reports	16:10
5.1 MEMS Microfluidics Task Force	
5.2 MEMS Substrate Task Force	
5.3 MEMS Material Characterization Task Force	
6 Break	16:30
7 Old Business	16:45



Time

8 New Business

17:00

8.1 Activity update between SEMI/MSIG TF and MSIG Core Standards WG

8.2 New TFOF(s) and/or SNARF(S)

8.3 Upcoming Ballot(s)

9 Action Item Review

17:15

9.1 Open Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
2017April#01	Rich Allen	To check if SEMI MS1 needs to be revised or looked at in conjunction with SEMI 3D15. CLOSED. Decided to send out for reapproval.
2017April#02	Laura Nguyen	To submit SEMIViews for 3D15 and MS1 to Rich, Mark, Win, and Steve. CLOSED.
2017April#03	Laura Nguyen	To create SNARFs for reapproval ballots. CLOSED.

9.2 New Action Items

10 Next Meeting and Adjournment

17:25

10.1 The next meeting is scheduled for Monday, November 6, 2017 at the SEMI Headquarters in Milpitas, California.

Monday, November 6

11:00-12:00 Microfluidics (TF)

13:30-15:30 Joint MSIG, MEMS Substrate, and Material Characterization

(TFs)

15:30-17:30 MEMS / NEMS (C)

2017/06/28
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